RENESAS

HD74LS156

Dual 2-line-to-4-line Decoders / Demultiplexers (with open collector outputs)

REJ03D0441-0300 Rev.3.00 Jul.13.2005

This circuit features dual 1-line-to-4-line demultiprexer with individual strobes and common binary-address input. When both sections are enabled by the strobes, the common binary-address inputs sequentially select and route associated input data to the appropriate output of each section. The individual strobes permit activating or inhibiting each of the 4-bit sections as desired. Data applied to input 1C is inverted through its outputs. The inverter following the 1C data input permits use as a 3-to-8-line decoder or 1-to-8-line demultiplexer without external gating.

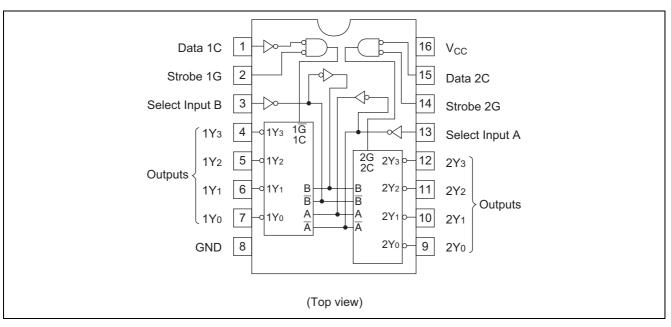
Features

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS156P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	Ρ	—
HD74LS156RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	FP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement





Function Table

• 2-to-4-line Decoder / 1-to-4-line Demultiplexer

	Inp	outs		Outputs					
S	elect	Strobe	Data	11	1Y ₁	1Y ₂	1Y ₃		
В	Α	1G	1C	- 1Y₀	111	112	113		
Х	Х	Н	Х	Н	Н	Н	Н		
L	L	L	Н	L	Н	Н	Н		
L	Н	L	Н	Н	L	Н	Н		
Н	L	L	Н	Н	Н	L	Н		
Н	Н	L	Н	Н	Н	Н	L		
Х	Х	Х	L	Н	Н	Н	Н		

	Inp	uts		Outputs					
Se	lect	Strobe	Data	2Y ₀	2Y ₁	2Y ₂	2Y ₃		
В	Α	2G	2C	210	211	212	213		
Х	Х	Н	Х	Н	Н	Н	Н		
L	L	L	L	L	Н	Н	Н		
L	Н	L	L	Н	L	Н	Н		
Н	L	L	L	Н	Н	L	Н		
Н	Н	L	L	Н	Н	Н	L		
Х	Х	Х	Н	Н	Н	Н	Н		

• 3-to-8-line Decoder / 1-to-8-line Demultiplexer

		Inputs		Outputs								
	Select Strobe or Data			(0)	(1)	(2)	(3)	(4)	(5)	(6)	(7)	
C * ¹	В	Α	G* ²	2Y ₀	2Y ₁	2Y ₂	2Y ₃	1Y₀	1Y ₁	1Y ₂	1Y ₃	
Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н	Н	
L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	
L	L	Н	L	Н	L	Н	Н	Н	Н	Н	Н	
L	Н	L	L	Н	Н	L	Н	Н	Н	Н	Н	
L	Н	Н	L	Н	Н	Н	L	Н	Н	Н	Н	
Н	L	L	L	Н	Н	Н	Н	L	Н	Н	Н	
Н	L	Н	L	Н	Н	Н	Н	Н	L	Н	Н	
Н	Н	L	L	Н	Н	Н	Н	Н	Н	L	Н	
Н	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	L	

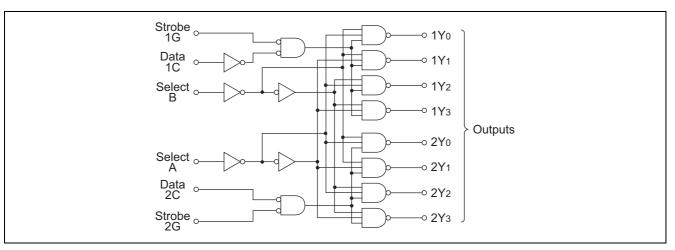
Notes: 1. C; input 1C and 2C connected together

2. G; inputs 1G and 2G connected together

3. H; high level, L; low level, X; irrelevant



Block Diagram



Absolute Maximum Ratings

ltem	Symbol	Ratings	Unit
Supply voltage	V _{CC}	7	V
Input voltage	V _{IN}	7	V
Power dissipation	PT	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{CC}	4.75	5.00	5.25	V
High level output voltage	V _{OH}	—	—	5.5	V
Low level output current	I _{OL}	—	—	8	mA
Operating temperature	Topr	-20	25	75	°C

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \ ^{\circ}\text{C})$

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V _{IH}	2.0	-	—	V	
Input voltage	VIL	—		0.8	V	
Output current	I _{OH}	—		100	μA	
	Max	—		0.4	V	$I_{OL} = 4 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, \text{ V}_{IH} = 2 \text{ V},$
Output voltage	V _{OL}	—		0.5	v	I _{OL} = 8 mA V _{IL} = 0.8 V
	I _{IH}	—		20	μΑ	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 2.7 \text{ V}$
Input current	I _{IL}	—		-0.4	mA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 0.4 \text{ V}$
	I _I	—		0.1	mA	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I} = 7 \text{ V}$
Supply current**	I _{CC}	_	6.1	10	mA	V _{CC} = 5.25 V
Input clamp voltage	V _{IK}	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, \text{ I}_{IN} = -18 \text{ mA}$

Notes: * $V_{CC} = 5 V$, Ta = 25°C

 ** I_{CC} is measured with outputs open, A, B, and 1C inputs at 4.5 V, and 2C, 1G, and 2G inputs grounded.



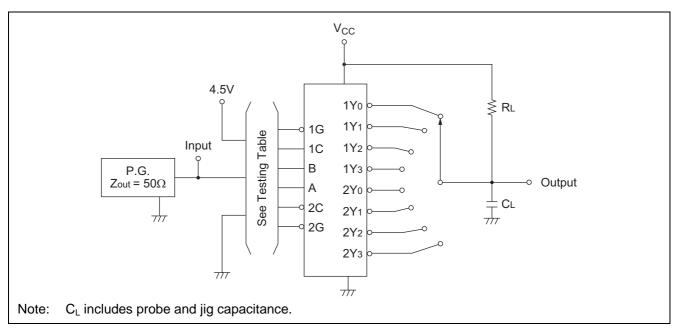
Switching Characteristics

 $(V_{CC} = 5 V, Ta = 25^{\circ}C)$

Item	Symbol	Inputs	Output	Level of logic	min.	typ.	max.	Unit	Condition
Propagation	t _{PLH}	A, B, 2C, 1G or 2G	Y	2	_	25	40		
	t _{PHL}	A, B, 2C, 1G or 2G	Y	2	—	34	51	ns	$C_L = 15 \text{ pF},$ $R_L = 2 \text{ k}\Omega$
delay time	t _{PLH}	A or B	Y	3	—	31	46		
	t _{PHL}	A or B	Y	3	—	34	51		
	t _{PLH}	1C	Y	3	_	32	48		
	t _{PHL}	1C	Y	3	—	32	48		

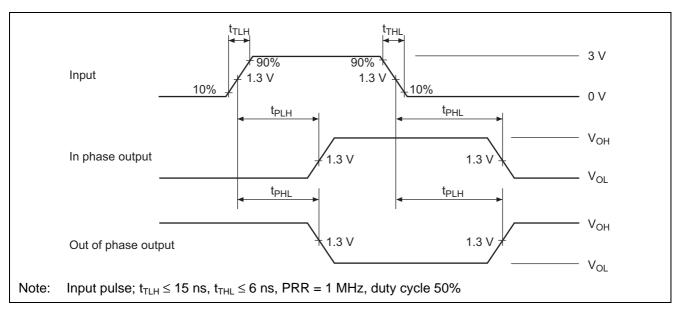
Testing Method

Test Circuit



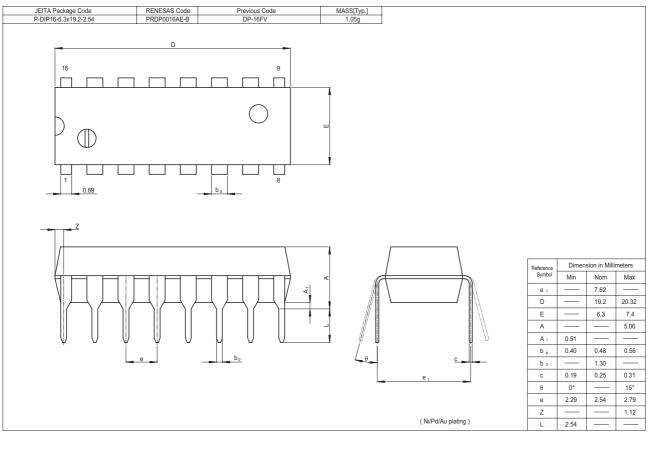


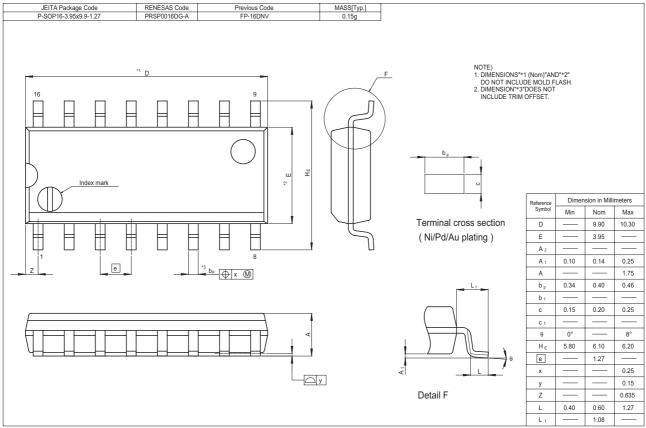
Waveform





Package Dimensions







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